

FS30ASJ-2

High-Speed Switching Use
Nch Power MOS FET

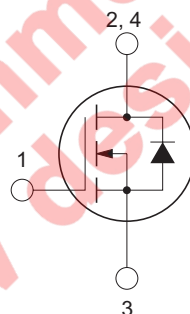
REJ03G1412-0200
(Previous: MEJ02G0064-0101)
Rev.2.00
Aug 07, 2006

Features

- Drive voltage : 4 V
- V_{DSS} : 100 V
- $r_{DS(ON) (max)}$: 84 m Ω
- I_D : 30 A
- Integrated Fast Recovery Diode (TYP.) : 80 ns

Outline

RENESAS Package code: PRSS0004ZA-A
(Package name: MP-3A)



1. Gate
2. Drain
3. Source
4. Drain

Applications

Motor control, Lamp control, Solenoid control, DC-DC converters, etc.

Maximum Ratings

(T_c = 25°C)

Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V_{DSS}	100	V	$V_{GS} = 0$ V
Gate-source voltage	V_{GSS}	±20	V	$V_{DS} = 0$ V
Drain current	I_D	30	A	
Drain current (Pulsed)	I_{DM}	120	A	
Avalanche drain current (Pulsed)	I_{DA}	30	A	L = 100 μ H
Source current	I_S	30	A	
Source current (Pulsed)	I_{SM}	120	A	
Maximum power dissipation	P_D	35	W	
Channel temperature	T _{ch}	– 55 to +150	°C	
Storage temperature	T _{stg}	– 55 to +150	°C	
Mass	—	0.32	g	Typical value

Electrical Characteristics

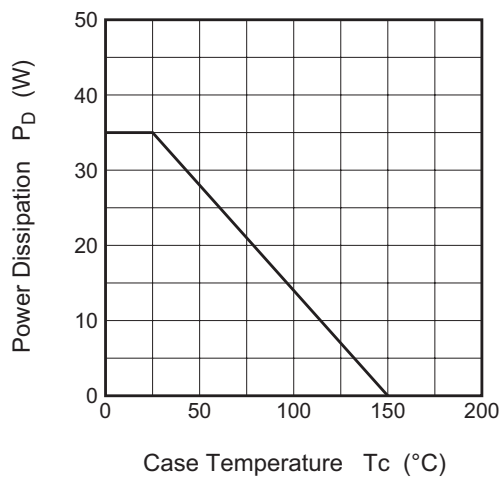
(Tch = 25°C)

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	—	—	V	$I_D = 1 \text{ mA}$, $V_{GS} = 0 \text{ V}$
Gate-source leakage current	I_{GSS}	—	—	± 0.1	μA	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0 \text{ V}$
Drain-source leakage current	I_{DSS}	—	—	0.1	mA	$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$
Gate-source threshold voltage	$V_{GS(th)}$	1.0	1.5	2.0	V	$I_D = 1 \text{ mA}$, $V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(on)}$	—	65	84	$\text{m}\Omega$	$I_D = 15 \text{ A}$, $V_{GS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(on)}$	—	70	91	$\text{m}\Omega$	$I_D = 15 \text{ A}$, $V_{GS} = 4 \text{ V}$
Drain-source on-state voltage	$V_{DS(on)}$	—	0.98	1.26	V	$I_D = 15 \text{ A}$, $V_{GS} = 10 \text{ V}$
Forward transfer admittance	$ y_{fs} $	—	23	—	S	$I_D = 15 \text{ A}$, $V_{DS} = 10 \text{ V}$
Input capacitance	C_{iss}	—	1800	—	pF	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$
Output capacitance	C_{oss}	—	230	—	pF	
Reverse transfer capacitance	C_{rss}	—	120	—	pF	
Turn-on delay time	$t_{d(on)}$	—	17	—	ns	$V_{DD} = 50 \text{ V}$, $I_D = 15 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_{GEN} = R_{GS} = 50 \Omega$
Rise time	t_r	—	46	—	ns	
Turn-off delay time	$t_{d(off)}$	—	135	—	ns	
Fall time	t_f	—	95	—	ns	
Source-drain voltage	V_{SD}	—	1.0	1.5	V	$I_S = 15 \text{ A}$, $V_{GS} = 0 \text{ V}$
Thermal resistance	$R_{th(ch-c)}$	—	—	3.57	$^{\circ}\text{C/W}$	Channel to case
Reverse recovery time	t_{rr}	—	80	—	ns	$I_S = 30 \text{ A}$, $dI_S/dt = -100 \text{ A}/\mu\text{s}$

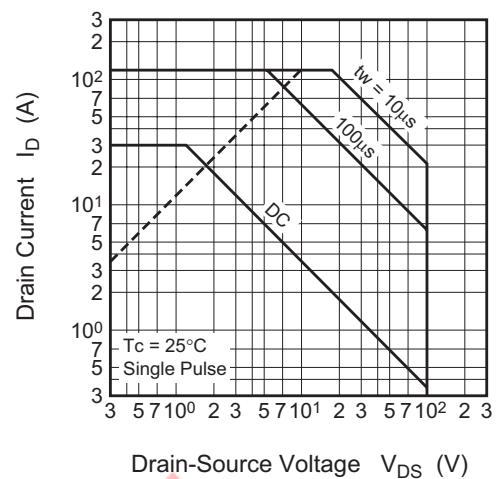
Not recommended
for new designs

Performance Curves

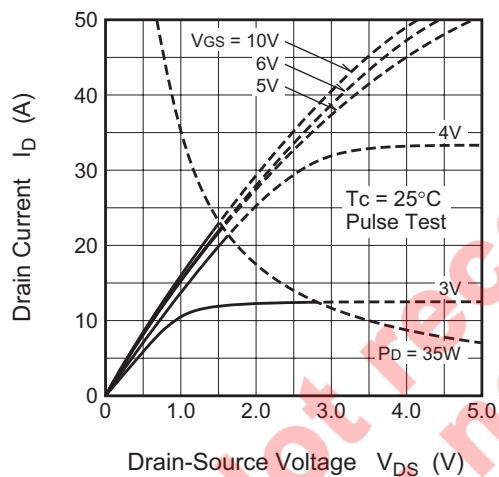
Power Dissipation Derating Curve



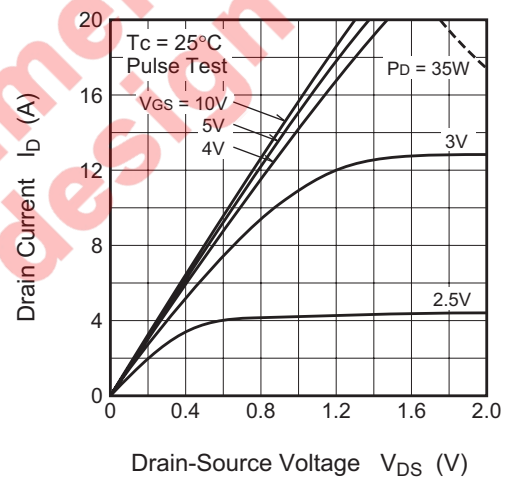
Maximum Safe Operating Area



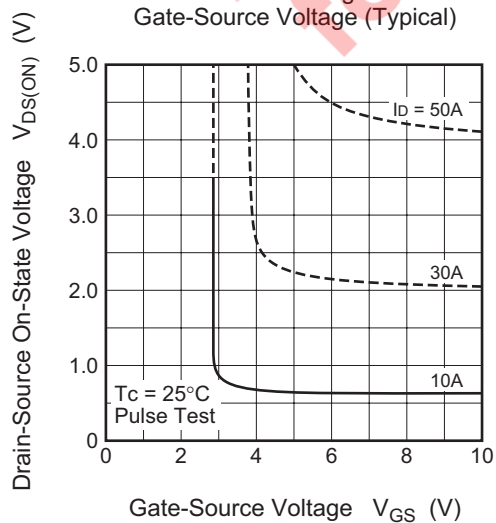
Output Characteristics (Typical)



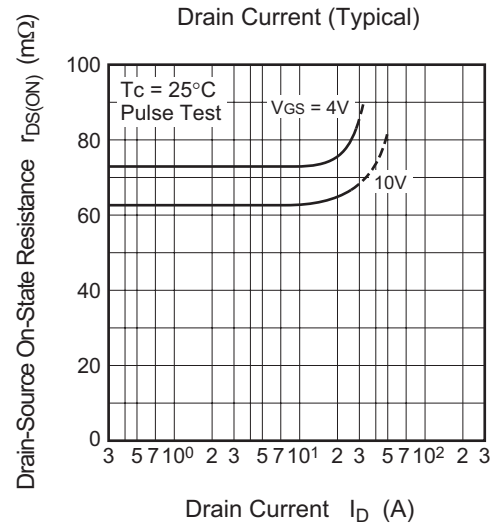
Output Characteristics (Typical)



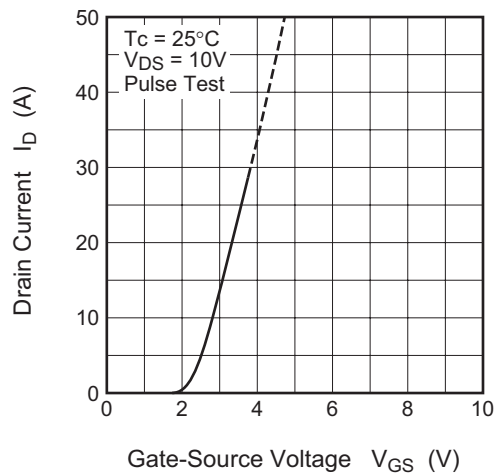
On-State Voltage vs. Gate-Source Voltage (Typical)



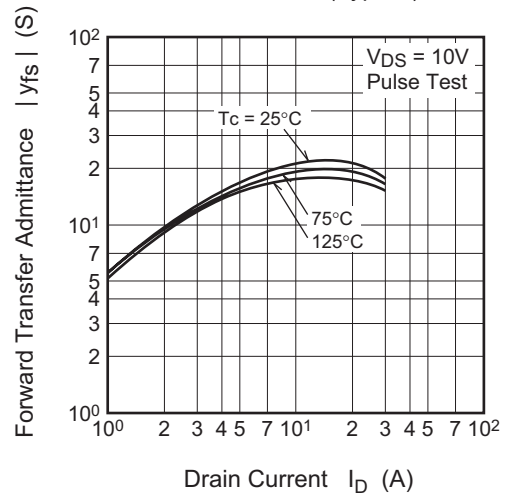
On-State Resistance vs. Drain Current (Typical)



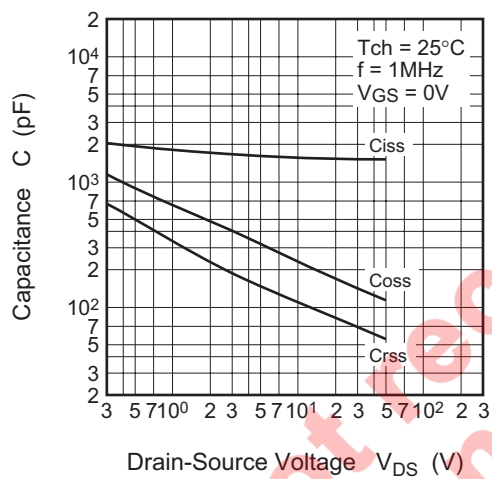
Transfer Characteristics (Typical)



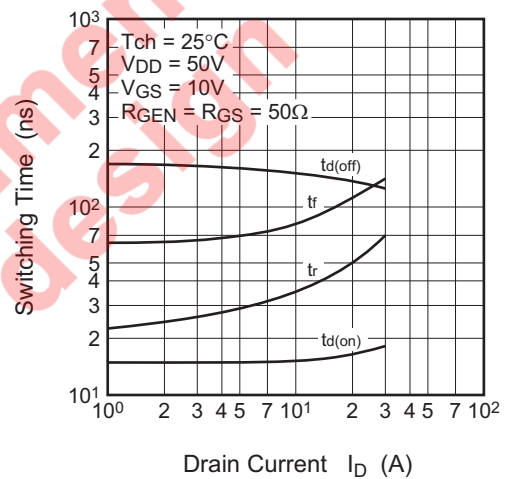
Forward Transfer Admittance vs. Drain Current (Typical)



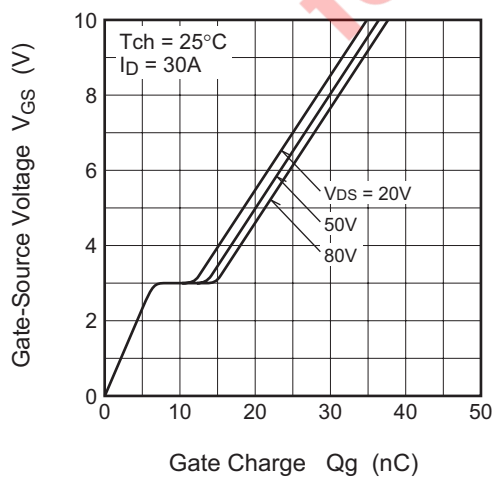
Capacitance vs. Drain-Source Voltage (Typical)



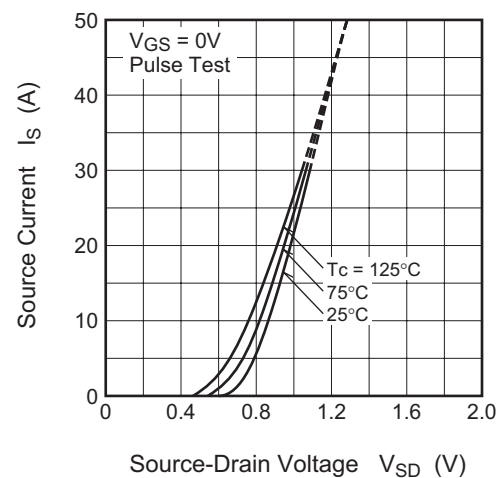
Switching Characteristics (Typical)

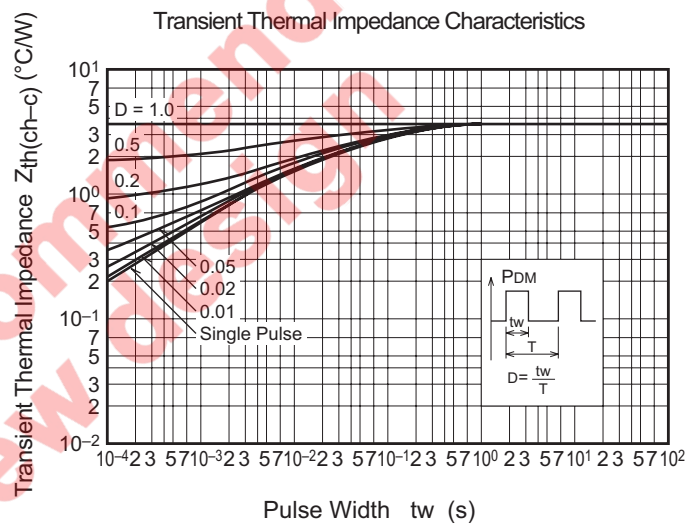
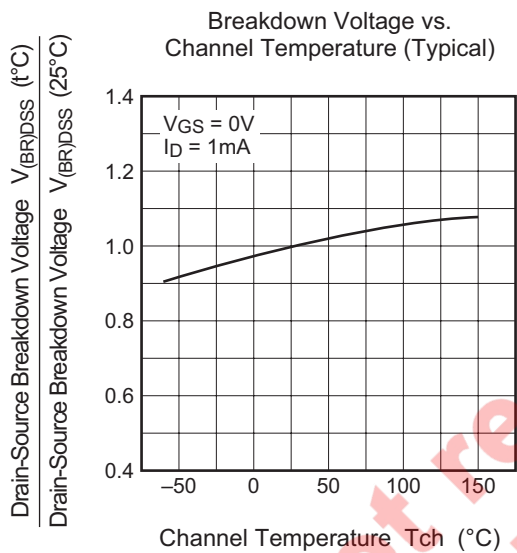
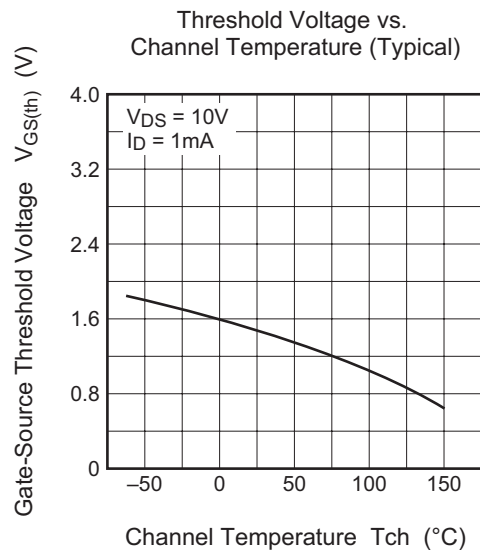
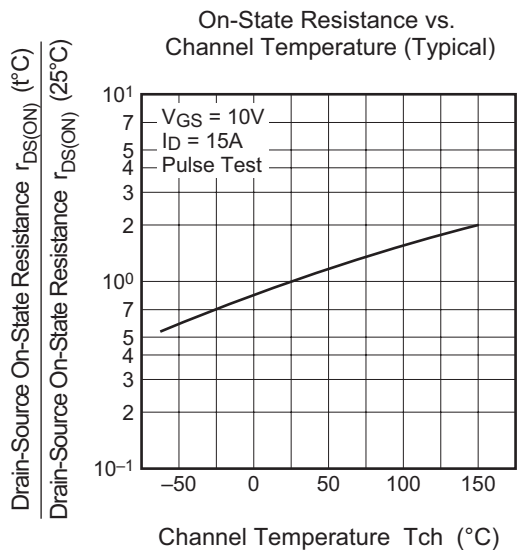


Gate-Source Voltage vs. Gate Charge (Typical)

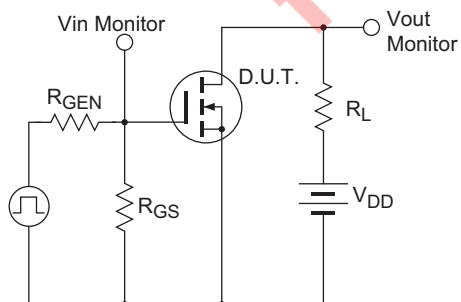


Source-Drain Diode Forward Characteristics (Typical)

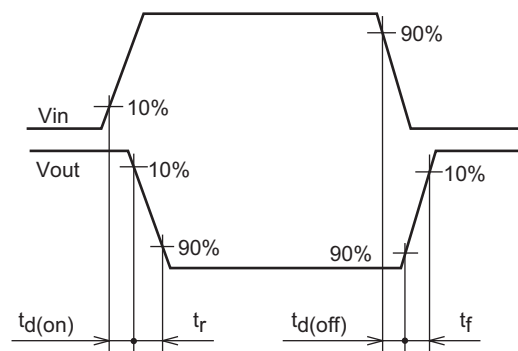




Switching Time Measurement Circuit



Switching Waveform



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]	Unit: mm
MP-3A	SC-63	PRSS0004ZA-A	—	0.32g	

The drawing shows three views of the package: top, side, and bottom. Dimensions are in mm.

- Top View:** Overall width 6.6, lead width 5.3 ± 0.2 , lead thickness 1 ± 0.2 , body width 6.1 ± 0.2 , total height 10.4Max , lead height 2.5Min , lead width 0.76 ± 0.2 , and lead pitch 2.3 ± 0.2 .
- Side View:** Lead height 2.3 , lead width 0.5 ± 0.2 , body width 0.1 ± 0.1 , lead height 1.4 ± 0.2 , and lead width 0.5 ± 0.2 .
- Bottom View:** Lead width 2.3 and lead height 1 .

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Surface-mounted type	Taping	3000	Type name – T +Direction (1 or 2) +3	FS30ASJ-2-T13
Surface-mounted type	Plastic Magazine (Tube)	75	Type name	FS30ASJ-2

Note : Please confirm the specification about the shipping in detail.

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